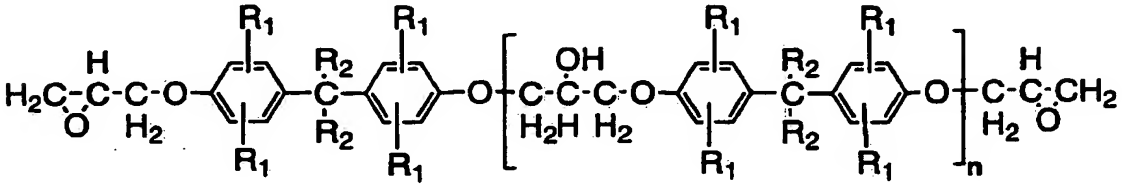
Abstract

The present invention relates to an epoxy resin composition for sealing photosemiconductor, the epoxy resin composition containing

(A) a bisphenol-type epoxy resin represented by the following formula (1)



(1)

(in the formula, R_1s represent hydrogen atom, a C1 - C8 alkyl group, a halogen atom; R_2s represent hydrogen atom, a C1 - C5 alkyl group, a halogen-substituted (C1 - C5) alkyl group or phenyl group; n represents an integer), where the ratio of the total content of such bisphenol-type lower molecular epoxy resins with n = 0, 1 or 2 is 10% by weight or more of the whole resin;

(B) a terpene backbone-containing polyvalent phenol curing agent prepared by adding two molecules of phenols to one molecule of a cyclic terpene compound;

(C) a curing-promoting agent;

(D) at least one resin selected from the group consisting of epoxy resins except for the component (A) and novolak resins

as a curing agent;

and an photosemiconductor device sealed with the cured material of the composition, where the composition has great workability and good productivity of sealed photosemiconductor, so that the resulting photosemiconductor sealed with the cured material of the composition has great solder reflow resistance after moisture absorption and good thermal resistance for HC.